



Material Composition Declaration

EPC2012

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	2.7 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	2.4719	90.28	92.60	902809
	Silicon oxide	7631-86-9	0.0095	0.35		3487
	Silicon nitride	12033-89-5	0.0030	0.11		1084
	Gallium nitride	25617-97-4	0.0180	0.66		6566
	Aluminum	7429-90-5	0.0184	0.67		6736
	Aluminum nitride	24304-00-5	0.0044	0.16		1611
	Titanium	7440-32-6	0.0004	0.01		131
	Titanium nitride	25583-20-4	0.0016	0.06		576
	Copper	7440-50-8	0.0006	0.02		224
	Tungsten	7440-33-7	0.0003	0.01		116
	Polyimide		0.0072	0.26		2626
Under Bump Metal	Titanium	7440-32-6	0.0004	0.01	0.16	132
	Nickel	7440-02-0	0.0011	0.04		394
	Vanadium	7440-62-2	0.0001	0.00		20
	Copper	7440-50-8	0.0029	0.10		1049
Solder Bump	Tin	7440-31-5	0.1894	6.92	7.24	69178
	Silver	7440-22-4	0.0079	0.29		2898
	Copper	7440-50-8	0.0010	0.04		362
Sum in total:			2.7	100	100	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.